

DERWENT-ACC-NO: 2002-537250

DERWENT-WEEK: 200649

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TITLE: Electroconductive metal paste and its production

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PRIORITY-DATA: 2001JP-0236650 (August 3, 2001) , 2000JP-0325414 (October 25, 2000)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
US 7081214 B2	July 25, 2006	N/A	000	C09D 005/24
WO <u>200235554</u> A1	May 2, 2002	J	068	H01B 001/22
AU 200190266 A	May 6, 2002	N/A	000	H01B 001/22
EP 1339073 A1	August 27, 2003	E	000	H01B 001/22
US 20040004209 A1	January 8, 2004	N/A	000	H01B 001/02
JP 2002538446 X	March 4, 2004	N/A	000	H01B 001/22
CN 1478285 A	February 25, 2004	N/A	000	H01B 001/22
KR 2004030441 A	April 9, 2004	N/A	000	H01B 001/22
TW 591095 A	June 11, 2004	N/A	000	C09J 009/02

DESIGNATED-STATES: AE AG AL AM AT AU AZ BA BB BG BR BY BZ CA CH CN CO CR CU CZ DE DK DM DZ EC EE ES FI GB GD GE GH GM HR HU ID IL IN IS JP KE KG KP KR KZ LC LK LR LS LT LU LV MA MD MG MK MN MW MX MZ NO NZ PH PL PT RO RU SD SE SG SI SK SL TJ TM TR TT TZ UA UG US UZ VN YU ZA ZW AT BE CH CY DE DK EA ES FI FR GB GH GM GR IE IT KE LS LU MC MW MZ NL OA PT SD SE SL SZ TR TZ UG ZW AL AT BE CH CY DE DK ES FI FR GB GR IE IT LI LT LU LV MC MK NL PT RO SE SI TR

APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-NO	APPL-DATE
US 7081214B2	N/A	2001WO-JP08340	September 26, 2001
US 7081214B2	N/A	2003US-0415004	April 21, 2003
US 7081214B2	Based on	<u>WO 200235554</u>	N/A
WO 200235554A1	N/A	2001WO-JP08340	September 26, 2001
AU 200190266A	N/A	2001AU-0090266	September 26, 2001
AU 200190266A	Based on	<u>WO 200235554</u>	N/A

EP 1339073A1	N/A	2001EP-0970208	September 26, 2001
EP 1339073A1	N/A	2001WO-JP08340	September 26, 2001
EP 1339073A1	Based on	WO <u>200235554</u>	N/A
US20040004209A1	N/A	2001WO-JP08340	September 26, 2001
US20040004209A1	N/A	2003US-0415004	April 21, 2003
JP2002538446X	N/A	2001WO-JP08340	September 26, 2001
JP2002538446X	N/A	2002JP-0538446	September 26, 2001
JP2002538446X	Based on	WO <u>200235554</u>	N/A
CN 1478285A	N/A	2001CN-0819671	September 26, 2001
KR2004030441A	N/A	2003KR-0705738	April 25, 2003
TW 591095A	N/A	2001TW-0123742	September 26, 2001

INT-CL (IPC): B05D007/00, B22F001/02, C08K003/00, C08K005/00, C08K009/04, C08L101/00, C09D005/24, C09J009/02, C09J201/00, C22C009/00, H01B001/00, H01B001/02, H01B001/22, H01B013/00, H05K001/09

ABSTRACTED-PUB-NO: WO 200235554A

BASIC-ABSTRACT:

NOVELTY - An electroconductive metal paste which comprises a resin composition comprising a thermosetting resin component, an organic acid anhydride or a derivative thereof of an organic acid and one or more organic solvents and, dispersed homogeneously therein, as an electroconductive medium, ultra-fine metal particles having an average particle diameter of 100 nm or less and being surface-coated with one or more compounds having a group capable of forming a coordinate-type bonding with a metal element contained in said ultra-fine metal particle through a lone electron pair of N, O or S, optionally combined with a metal filler having an average particle diameter of 0.5 to 20 microns .

USE - For forming a fine circuit having low resistance and for printing a high density circuit.

ADVANTAGE - The electroconductive metal paste is of a low-temperature sintering type, and exhibits good adhesion and a smooth surface when applied on a substrate and burned. and thus can be used

CHOSEN-DRAWING: Dwg.0/0

TITLE-TERMS: ELECTROCONDUCTING METAL PASTE PRODUCE

DERWENT-CLASS: A85 L03 P42 P53 V04 X12

CPI-CODES: A99-A; L03-A01A3; L03-H04E4;

EPI-CODES: V04-R02P; X12-D01X;